SDAS123A - DECEMBER 1983 - REVISED JANUARY 1995

 Bidirectional Bus High-Density 20-Pi 		DW OR N PACKAGE (TOP VIEW)		
 Choice of True or I A-Bus Outputs Are B-Bus Outputs Are 	e Open Collec	DIR 1 20 V _{CC} A1 2 19 OE A2 3 18 B1		
 Package Options I Small-Outline (DW Standard Plastic (N) Packages a	nd		A3 [] 4 17] B2 A4 [] 5 16] B3 A5 [] 6 15] B4 A6 [] 7 14] B5
DEVICE	A OUTPUT	B OUTPUT	LOGIC	A7 [] 8 13] B6 A8 [] 9 12 [] B7
SN74ALS638A, SN74AS638A	Open collector	3 state	Inverting	GND [] 10 11 [] B8
SN74ALS639A, SN74AS639	Open collector	3 state	True	

description

These octal bus transceivers are designed for asynchronous two-way communication between open-collector and 3-state buses. The devices transmit data from the A bus (open-collector) to the B bus (3 state) or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are isolated.

The -1 version of SN74ALS638A is identical to the standard version, except that the recommended maximum I_{OL} is increased to 48 mA.

The SN74ALS638A, SN74ALS639A, SN74AS638A, and SN74AS639 are characterized for operation from 0°C to 70°C.

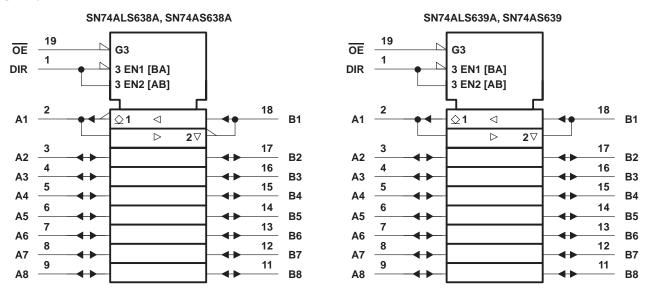
1	NPUTS	OPERATION									
OE	DIR	SN74ALS638A SN74AS638A	SN74ALS639A SN74AS639								
L	L	B data to A bus	B data to A bus								
L L	Н	A data to B bus	A data to B bus								
н	Х	Isolation	Isolation								

FUNCTION TABLE



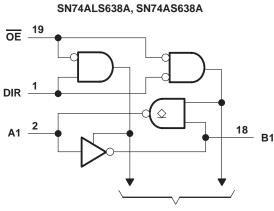
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logic symbols[†]

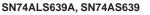


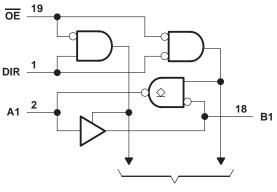
[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



To Seven Other Transceivers





To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V _I : All inputs	V
A-bus I/O ports	V
B-bus I/O ports 5.5	
Operating free-air temperature range, T _A : SN74ALS638A, SN74ALS639A 0°C to 70°	С
Storage temperature range	С

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

			-	74ALS63 74ALS63	-	UNIT
			MIN	NOM	MAX	
VCC	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	V
∨он	High-level output voltage	A ports			5.5	V
ЮН	High-level output current	B ports			-15	mA
1		A or D porto			24	
IOL	Low-level output current	A or B ports			48†	mA
ТА	Operating free-air temperature				70	°C

[†] Applies only to the SN74ALS638A-1 version and only if V_{CC} is between 4.75 V and 5.25 V

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDI	TEST CONDITIONS				UNIT	
			MIN	typ‡	MAX			
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.5	V	
IOH	A ports	$V_{CC} = 4.5 V,$	V _{OH} = 5.5 V			0.1	mA	
		V_{CC} = 4.5 V to 5.5 V,	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2			
VOH	B ports	V _{CC} = 4.5 V	I _{OH} = -3 mA	2.4	3.2		V	
		VCC = 4.3 V	I _{OH} = -15 mA	2				
			I _{OL} = 12 mA		0.25	0.4		
VOL	A or B ports	$V_{CC} = 4.5 V$	I _{OL} = 24 mA		0.35	0.5	V	
			I _{OL} = 48 mA [†]		0.35	0.5		
1.	Control inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1	mA	
lj	A or B ports	VCC = 5.5 V	V _I = 5.5 V			0.1	ША	
1	Control inputs		V ₁ = 2.7 V			20	μA	
IН	A or B ports§	V _{CC} = 5.5 V,	V = 2.7 V			20	μA	
1	Control inputs		V ₁ = 0.4 V			-0.1	mA	
۱Ľ	A or B ports§	V _{CC} = 5.5 V,	v] = 0.4 v			-0.1	ШA	
IO	B ports	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA	
			Outputs high		18	30		
	SN74ALS638A	$V_{CC} = 5.5 V$	Outputs low		26	41	mA	
100			Outputs disabled		16	30		
ICC			Outputs high		25	40		
	SN74ALS639A	$V_{CC} = 5.5 V$	Outputs low		30	50		
			Outputs disabled		33	54	1	

 † Applies only to the SN74ALS638A-1 version and only if V_{CC} is between 4.75 V and 5.25 V

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C. § For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L = 50 R _L = 68 R1 = R	30 Ω (A o	outputs), 2 (B outpu	uts),	UNIT	
			SN74AL	S638A	SN74AL	S639A		
			MIN	MAX	MIN	MAX		
^t PLH	А		2	12	2	12	ns	
^t PHL	A	В	2	12	2	12	115	
^t PLH	В		8	25	10	30	20	
^t PHL	D	A	8	30	5	22	ns	
^t PLH	OE		5	25	10	30		
^t PHL	OE	A	10	45	10	35	ns	
^t PZH			5	20	6	21		
tPZL	OE	В	5	22	8	25	ns	
^t PHZ	OE	D	2	10	2	10		
^t PLZ	UE	В	3	15	3	16	ns	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V _I : All inputs	
A-bus I/O ports	
B-bus I/O ports	5.5 V
Operating free-air temperature range, TA: SN74AS638A, SN74AS639	0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			-	74AS638 174AS63	-	UNIT
			MIN	NOM	MAX	1
Vcc	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	V
VOH	High-level output voltage	A ports			5.5	V
ЮН	High-level output current	B ports			-15	mA
I _{OL}	Low-level output current	A or B ports			64	mA
TA	Operating free-air temperature		0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDI	TEST CONDITIONS				UNIT
			MIN	MIN TYP [†] M			
VIK		V _{CC} = 4.5 V,	lj = –18 mA			-1.2	V
ЮН	A ports	V _{CC} = 4.5 V,	V _{OH} = 5.5 V			0.1	mA
		$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		
VOH	B ports		I _{OH} = -3 mA	2.4	3.2		V
		$V_{CC} = 4.5 V$	I _{OH} = -15 mA	2.4			
VOL	A or B ports	V _{CC} = 4.5 V,	I _{OL} = 64 mA		0.35	0.55	V
L	Control inputs		V _I = 7 V	0.1		0.1	mA
1	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1	mA
1	Control inputs					20	A
ЧH	A or B ports [‡]	V _{CC} = 5.5 V,	V ₁ = 2.7 V			70	μA
L.	Control inputs					-0.5	4
ΊL	A or B ports [‡]	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.75	mA
IO§		V _{CC} = 5.5 V,	V _O = 2.25 V	-50		-150	mA
			Outputs high		24	54	
	SN74AS638A	$V_{CC} = 5.5 V$	Outputs low		75	122	
			Outputs disabled		37	61	mA
lcc			Outputs high		56	92	
	SN74AS639	$V_{CC} = 5.5 V$	Outputs low		95	154	
			Outputs disabled		62	100	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

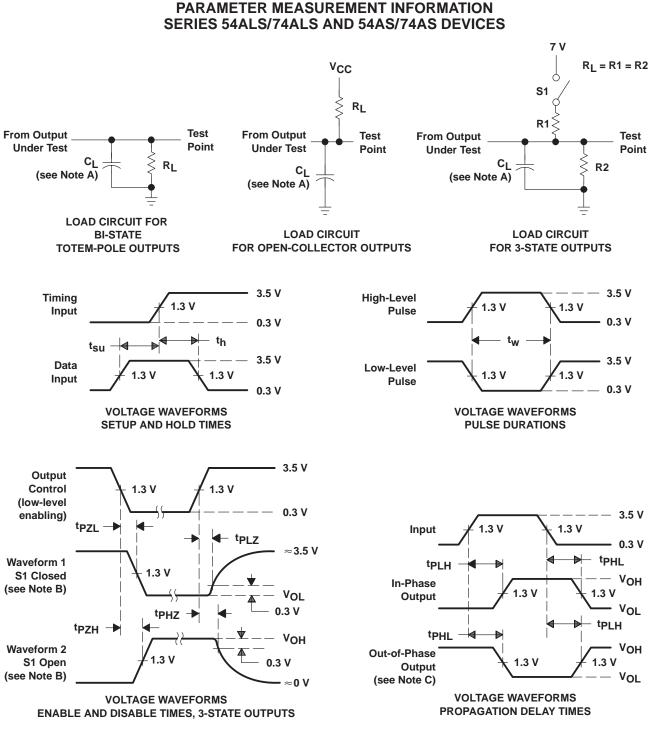
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L = 50 R _L = 50 R1 = R2 T _A = M	00 Ω (A d 2 = 500 Ω IN to MA	outputs) Ω (B out) \X¶	puts),	UNIT
			SN74A	S638A	SN74A	\S639	
			MIN	MAX	MIN	MAX	
^t PLH	А		2	7	2	9.5	ns
^t PHL	A	В	2	6.5	2	9	
^t PLH	В		5	20	5	22	ns
^t PHL	D	A	2	7	2	9	115
^t PLH			5	19	5	21.5	
^t PHL	OE	A	2	9	2	11.5	ns
^t PZH			2	8	2	10.5	
tPZL	OE	В	2	10	2	10.5	ns
^t PHZ	ŌĒ	В	2	7	2	7	ns
^t PLZ	UE	٥	2	10	2	10.5	

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS638AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS638AN	Samples
SN74ALS639ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS639A	Samples
SN74ALS639AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS639AN	Samples
SN74AS639DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS639DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS639N	OBSOLETE	E PDIP	Ν	20		TBD	Call TI	Call TI	0 to 70		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

11-Sep-2016

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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